

WE CLAIM:

1. A method of producing individual integrated circuit package units, comprising:

5 providing a base which includes a leadframe and a plurality of package precursors formed on said leadframe, each of said package precursors having inner leads and a semiconductor chip connected electrically to said inner leads, said leadframe having a plurality of
10 metallic connection bars extending along borderlines of said package precursors, and extension parts branching from two sides of said connection bars, said extension parts being formed integrally with said connection bars and being connected respectively and directly to said inner leads of said package precursors,
15 said extension parts being spaced apart from each other, said base further having a continuous encapsulating epoxy layer that encloses said semiconductor chips of said package precursors and that are bonded integrally with said leadframe; and

20 singulating said package precursors by cutting said leadframe and said encapsulating epoxy layer along first and second cutting streets which extend respectively along and at two opposite sides of said connection bars and which extend through said extension parts, wherein
25 the cutting of said base is performed by cutting into said first and second cutting streets with a cutting tool, thereby separating said connection bars from said

inner leads.

2. The method as claimed in Claim 1, wherein said package precursors are arranged in a grid-like array, said connection bars intersecting each other.

5 3. The method as claimed in Claim 1, wherein said cutting tool is a single-blade cutting tool.

4. The method as claimed in Claim 1, wherein said cutting tool is a dual-blade cutting tool.